

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (Canceled).
2. (Canceled).
3. (Canceled).
4. (Currently amended) The method of claim 310, wherein the layer of protective-carrier sheeting has a thickness in the range from 0.1 mm to 0.25 mm.
5. (Currently amended) The method of claim 310, wherein the conductive-foil sources are rolls of copper foil.
6. (Original) The method of claim 5, wherein the dielectric layer comprises prepreg.
7. (Original) The method as recited in claim 5, further comprising the steps of:
 - (d) placing the book in a lamination press; and
 - (e) pressing the book without inclusion of an adhesive or mechanical attachment between the protective-carrier sheeting and conductive foil.
8. (Canceled).
9. (Canceled).
10. (Previously presented) A method for producing laminates for printed wiring boards using protective-carrier sheeting, the method comprising the steps of:
 - (a) sandwiching a layer of protective-carrier sheeting between two layers of conductive

foil extended from one or more conductive-foil sources, wherein a layer of the conductive foil and the protective-carrier sheeting are unwound from a common roll, and wherein the conductive foil comprises copper, and the protective-carrier sheeting comprises aluminum and has a thickness in the range from about 0.08 mm to about 0.5 mm;

(b) covering one of the conductive-foil layers with a dielectric layer to sandwich the covered conductive-foil layer between the dielectric layer and the layer of protective-carrier sheeting; and

(c) repeating steps (a) and (b) and stacking the layers to form a book without the conductive-foil layers being bonded to the protective-carrier sheeting or to the dielectric layer.

11. (Canceled).

12. (Canceled).

13. (Canceled).

14. (Canceled).

15. (Canceled).

16. (Currently amended) The method of claim ~~15~~22, wherein the layer of protective-carrier sheeting has a thickness in the range from 0.1 mm to 0.25 mm.

17. (Currently amended) The method of claim ~~15~~22, wherein the conductive-foil sources comprise rolls of copper foil.

18. (Currently amended) The method of claim ~~15~~22, wherein the dielectric layer comprises prepreg.

19. (Currently amended) The method as recited in claim ~~15~~22, further comprising the steps of:

(d) placing the book in a lamination press; and
(e) pressing the book without inclusion of an adhesive or mechanical attachment between the protective-carrier sheeting and conductive foil.

20. (Canceled).

21. (Canceled).

22. (Previously presented) A method for producing laminates for printed wiring boards using protective-carrier sheeting, the method comprising the steps of:

(a) sandwiching a dielectric layer between two layers of conductive foil extended from conductive-foil sources, wherein at least one of the layers of conductive foil is covered by a layer of protective carrier sheeting, and wherein the covered layer of conductive foil and the covering layer of protective-carrier sheeting are unwound and extended from a common roll, and wherein the conductive foil comprises copper, and the protective-carrier sheeting comprises aluminum and has a thickness in the range from about 0.08 mm to about 0.5 mm; and

(b) repeating step (a) and stacking the layers to form a book, wherein each layer of conductive foil is sandwiched between a dielectric layer and a layer of protective-carrier sheeting without the conductive-foil layers being bonded to the protective-carrier sheeting or to the dielectric layer.

23. (Canceled).

24. (Canceled).

25. (Canceled).